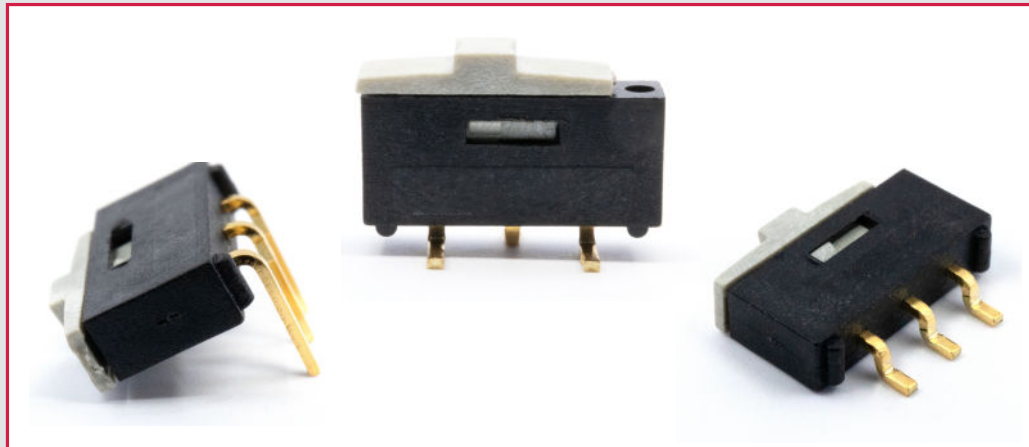
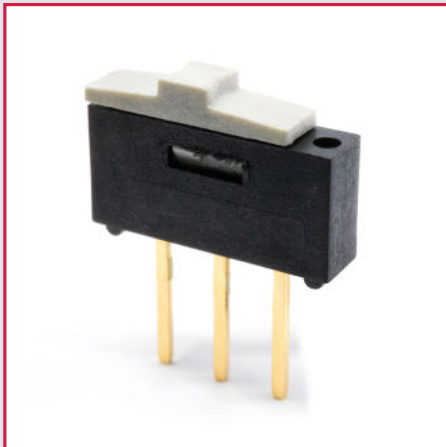


EGJ1210 SERIES SLIDE SWITCH



SPECIFICATIONS

Contact Rating: 300mA @ 24VDC
Electrical Life: 2,000 Cycles
Mechanical Life: 10,000 Cycles
Contact Resistance: 30mΩ Max
Insulation Resistance: 10,000MΩ Min @ 500VDC
Dielectric Strength: 500VAC for 1 Minute
Operating Temperature: -40°C to 85°C
Storage Temperature: -40°C to 85°C
Travel: 1.60mm
Contact Arrangement: SPDT

FEATURES & BENEFITS

Surface mount and Through Hole PC board design
1.60mm travel
Compact design
250 gram force
SPDT function

PART NUMBER CONFIGURATOR

Series	Actuator	Function	Terminal	Packaging
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EGJ1210	A - 1.40mm	A - SPDT	T1 - Through Hole T2 - Through Hole, Right Angle G1 - Gull Wing G2 - Gull Wing, Right Angle	(Blank) - Bulk R - Tape and Reel (Gull Wing Only)

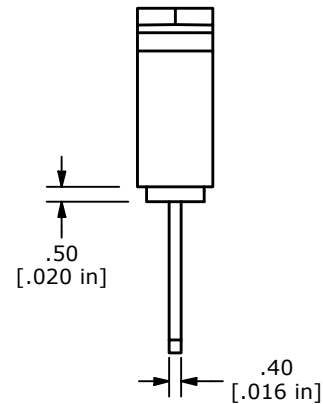
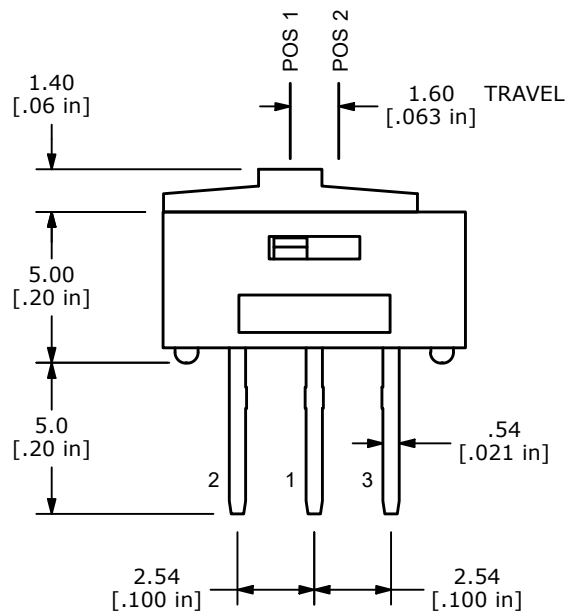
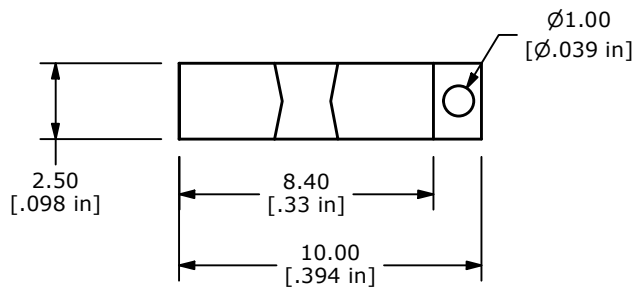
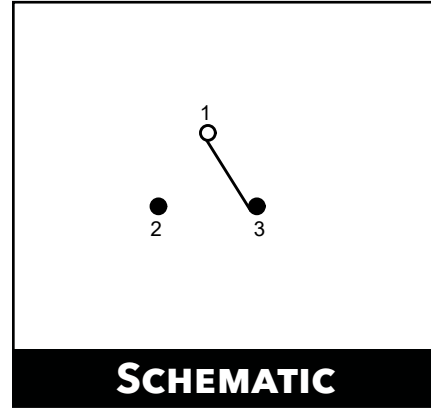
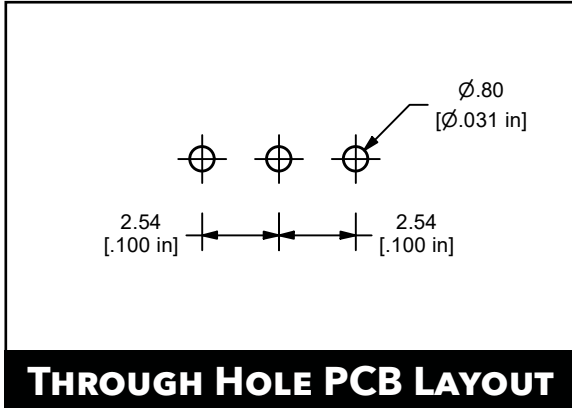
NOTES:
*Any additional information or clarifications

Specifications subject to change without notice 10/29/2024



EGJ1210 SERIES SLIDE SWITCH

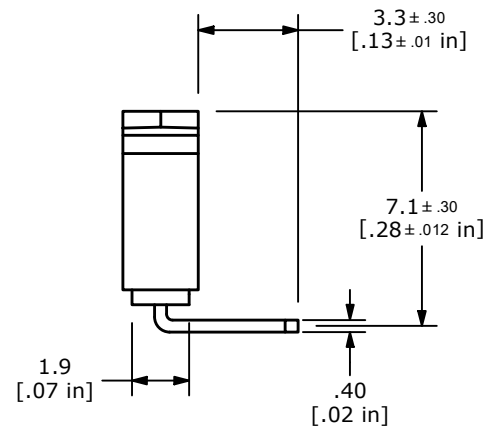
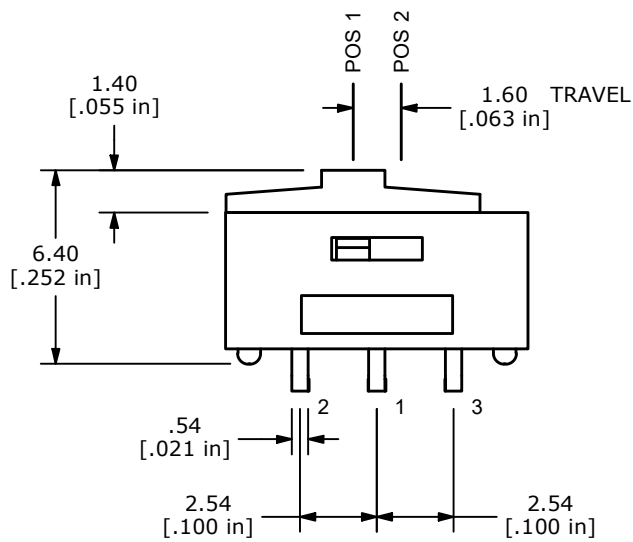
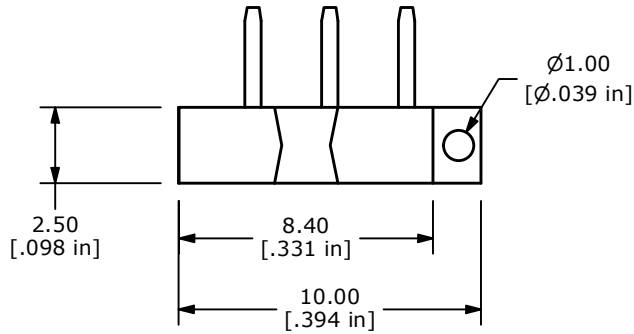
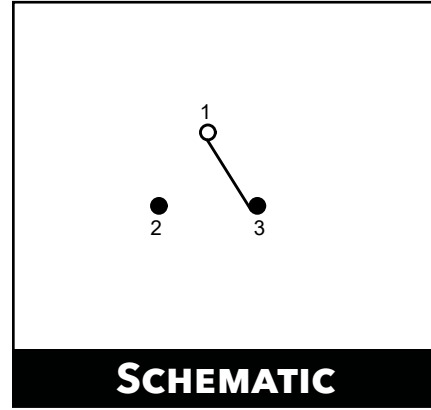
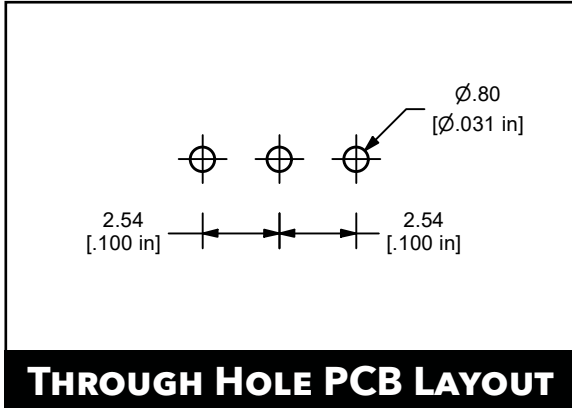
BODY DIMENSIONS





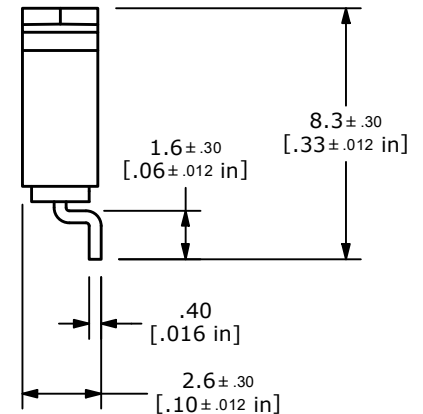
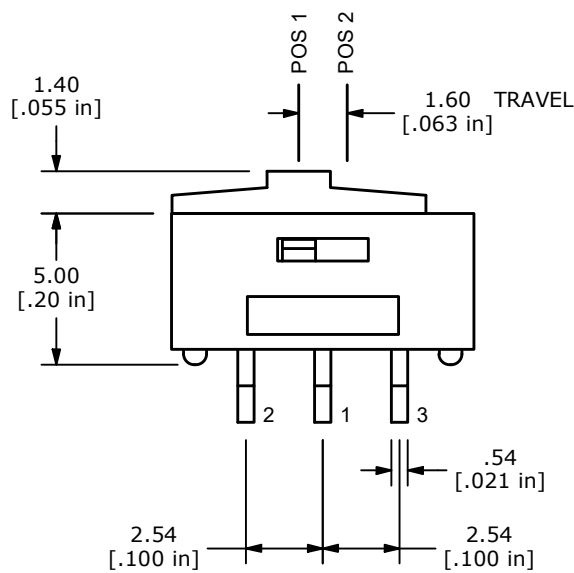
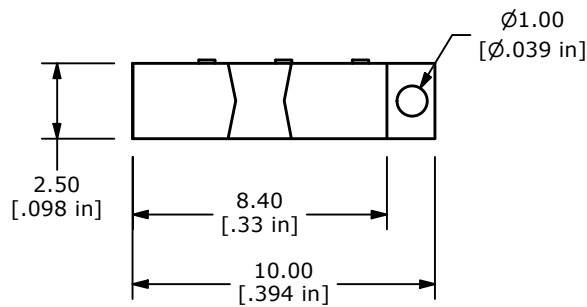
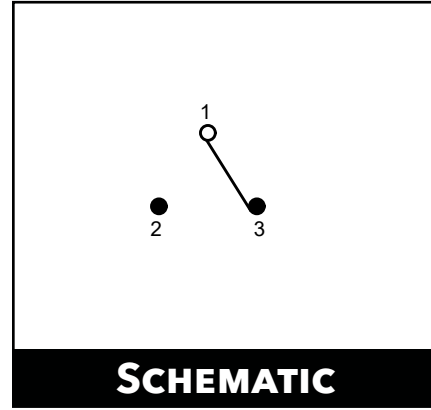
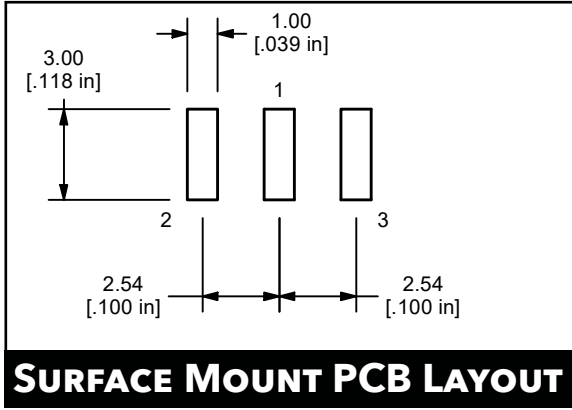
EGJ1210 SERIES SLIDE SWITCH

BODY DIMENSIONS



EGJ1210 SERIES SLIDE SWITCH

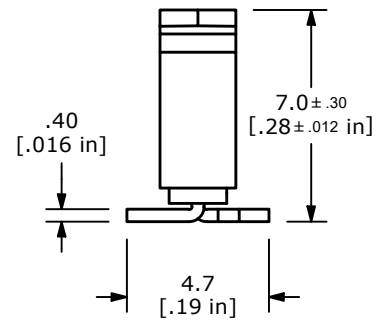
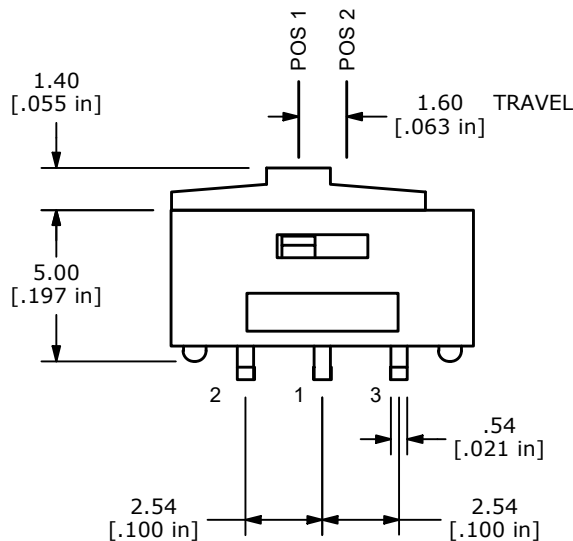
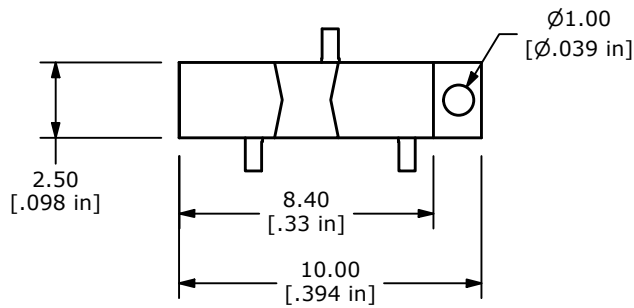
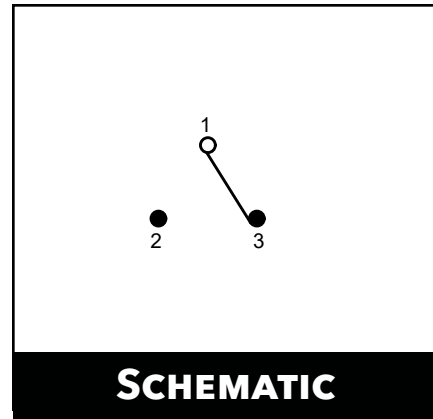
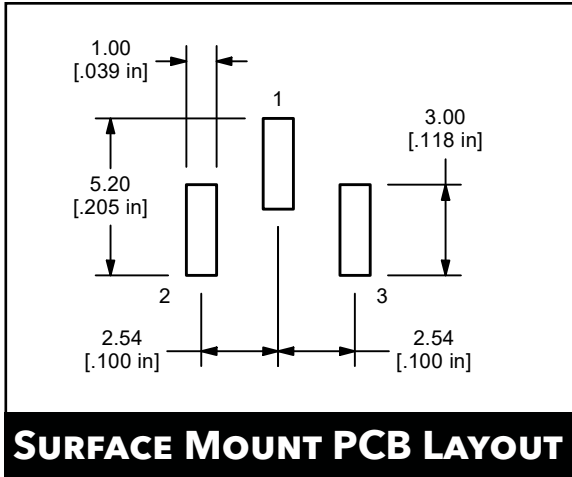
BODY DIMENSIONS





EGJ1210 SERIES SLIDE SWITCH

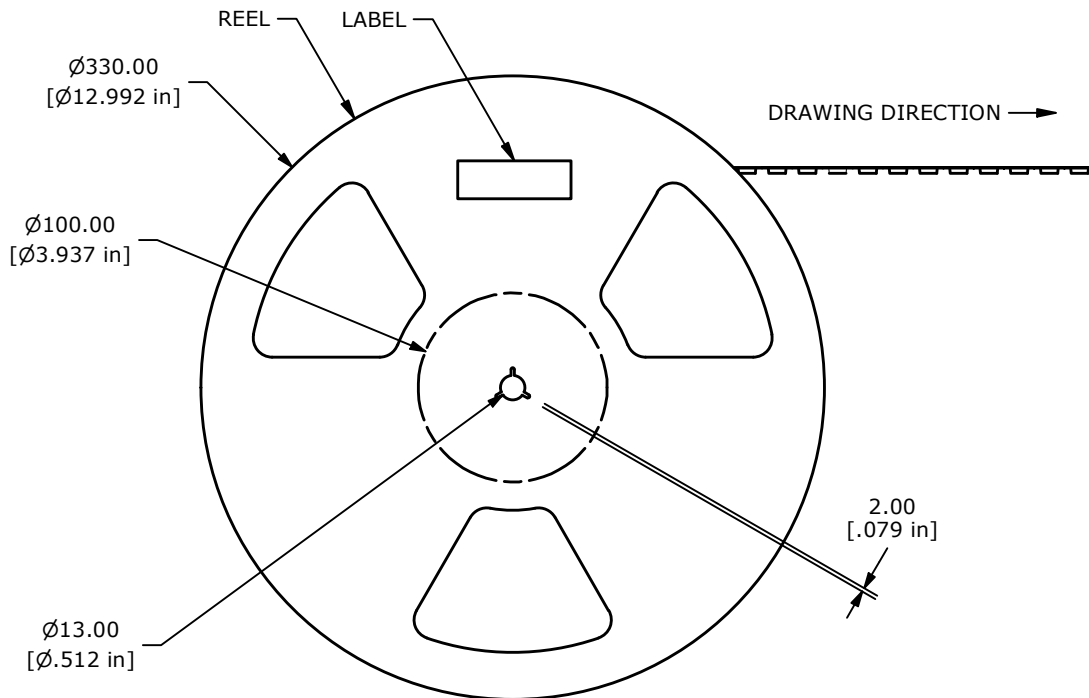
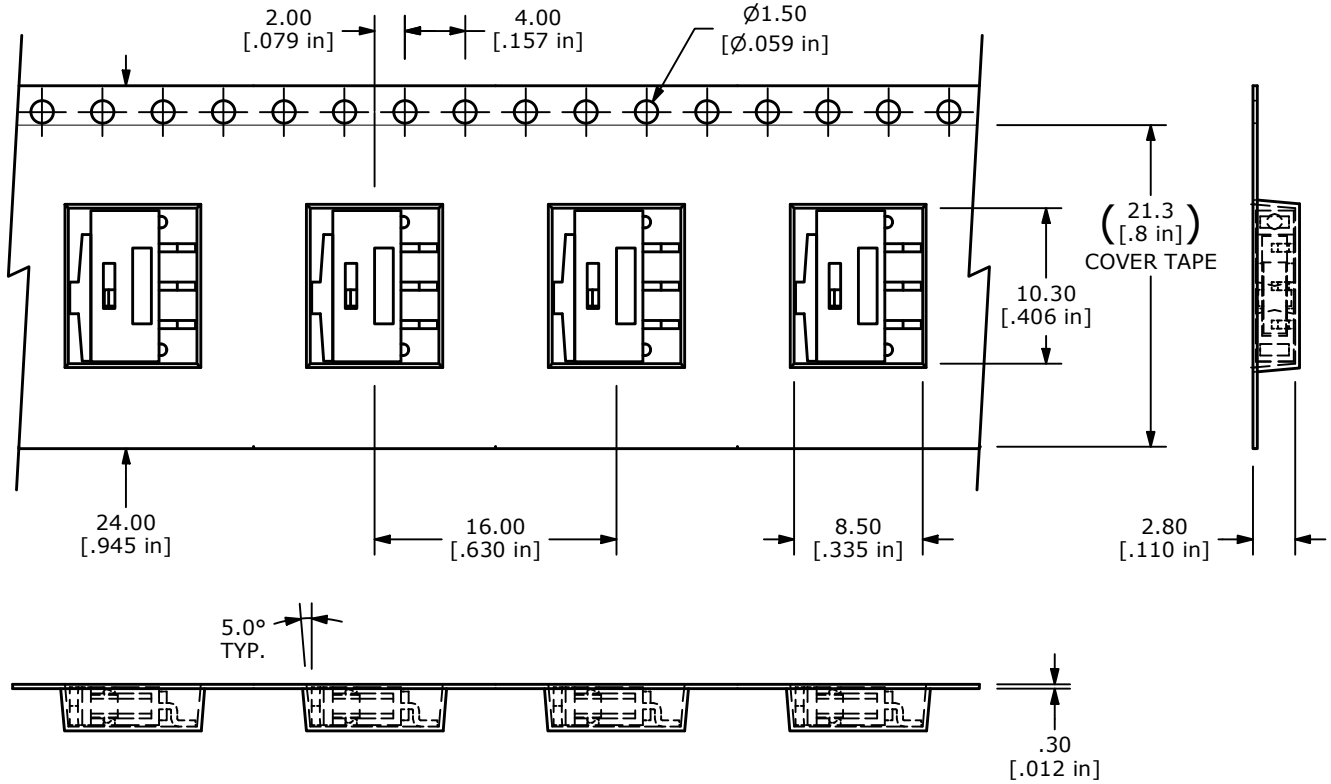
BODY DIMENSIONS





EGJ1210 SERIES SLIDE SWITCH

BODY DIMENSIONS TAPE AND REEL





EGJ1210 SERIES SLIDE SWITCH

RECOMMENDED SOLDER PROCESS

Most contamination problems can be prevented by exercising care during the cleaning and soldering process. Care should be taken not to immerse or spray unsealed switches during flux removal. Contact E-Switch for specific soldering recommendations and specifications not shown. Generalized soldering procedures are outlined below.

“TYPICAL” SMT REFLOW (Pb and Pb-Free)

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate ($T_{s_{max}}$ to T_p)	3 °C/second max.	3 °C/second max.
Preheat		
-Temperature Min ($T_{s_{min}}$)	100 °C	150 °C
-Temperature Max ($T_{s_{max}}$)	150 °C	200 °C
-Time ($t_{s_{min}}$ to $t_{s_{max}}$)	60-120 seconds	60-180 seconds
Time Maintained above:		
-Temperature (T_L)	183 °C	217 °C
-Time (t_L)	60-150 seconds	60-150 seconds
Time within 5 °C of actual Peak Temperature (t_p)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package surface.

